

This document can handle board shapes up to 7.9in x 10in, although our panel vendors top out at 7in x 10in.

To re-size the board shape, do the following:

Select lines on MI Board Outline and delete (easy in single layer mode...shift+s)

Draw a rectangle using lines (example will be for a 4 x 6 board)

Enter Place Line mode (keyboard pl)

keyboard jo to jump to origin, hit enter

keyboard jl to jump to location, set x to 6000, hit enter twice

keyboard jl to jump to location, set x to 6000 and y to 4000, hit enter twice

keyboard jl to jump to location, set x to 0 and y to 4000, hit enter twice

keyboard jo to jump to origin, hit enter

Hit ESC twice to exit place line mode

Select lines on MI Board Outline

Menu DesignBoard ShapeDefine from Selected Objects (keyboard dsd)

To define a Keep-Out that mirrors the board outline:

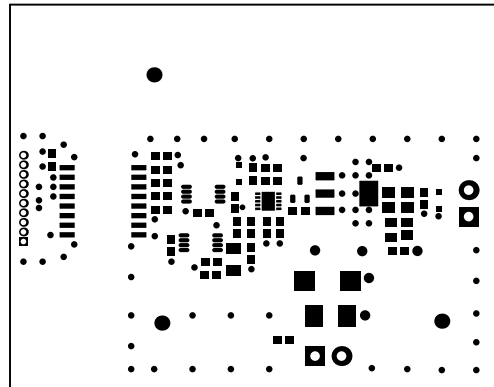
Menu DesignBoard ShapeCreate Primitives From Board Shape (keyboard dsp)

Set the Keep-Out Layer as the layer, set width as preferred

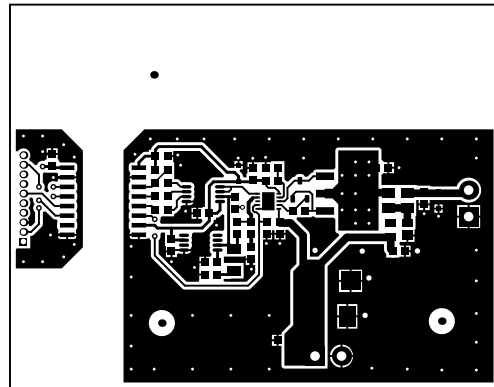
Ensure Route Tool Outline is selected, hit enter

If you re-size the board, don't forget to move the drill table strings on the Drill Drawing Layer...they should be just to the right of your board shape

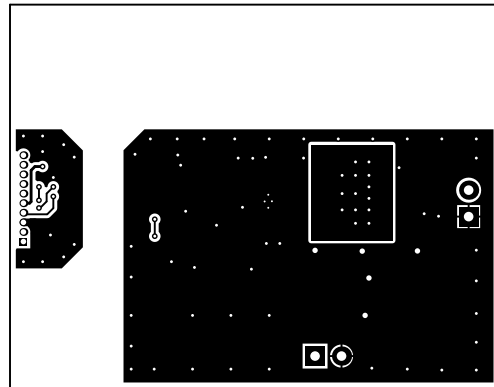
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01536	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01536		
PLOT NAME = Top Overlay	GENERATED : 7/28/2017 1:22:21 PM	TEXAS INSTRUMENTS	



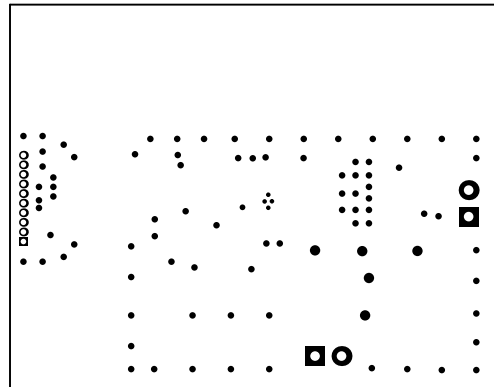
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01536	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01536		
PLOT NAME = Top Solder Mask	GENERATED : 7/28/2017 1:22:22 PM	TEXAS INSTRUMENTS	



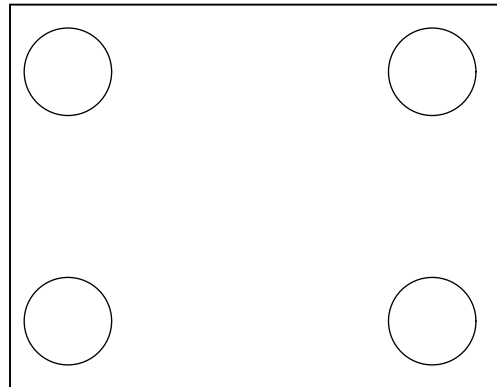
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01536	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01536		
PLOT NAME = Top Layer	GENERATED : 7/28/2017 1:22:24 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01536	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01536		
PLOT NAME = Bottom Layer	GENERATED : 7/28/2017 1:22:25 PM	TEXAS INSTRUMENTS	

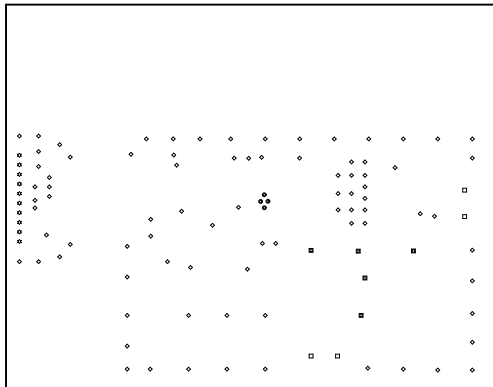


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01536	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01536		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/28/2017 1:22:27 PM	TEXAS INSTRUMENTS	

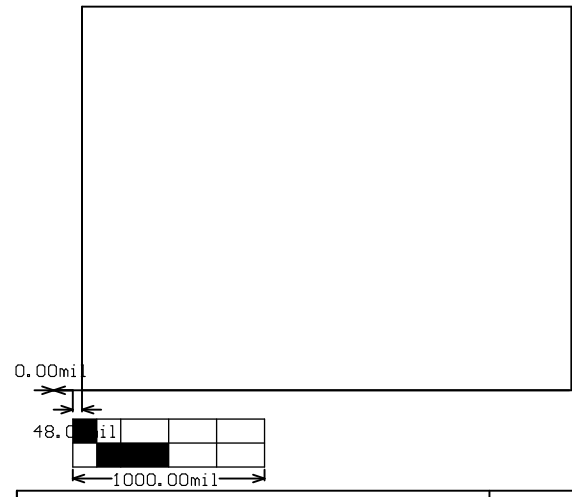


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01536	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01536		
PLOT NAME = Bottom Overlay	GENERATED : 7/28/2017 1:22:28 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
●	4	10.00mil (0.254mm)	PTH	Round
◇	83	15.00mil (0.381mm)	PTH	Round
■	5	28.00mil (0.711mm)	PTH	Round
✱	10	28.74mil (0.730mm)	PTH	Round
□	4	50.00mil (1.270mm)	PTH	Round
106 Total				



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01536	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01536		
PLOT NAME = Drill Drawing	GENERATED : 7/28/2017	1:22:29 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01536	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01536		
PLOT NAME = Board Dimensions	GENERATED : 7/28/2017 1:22:31 PM	TEXAS INSTRUMENTS	

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